



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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2SA1123

Silicon PNP epitaxial planar type

For low-frequency high breakdown voltage amplification
Complementary to 2SC2631

■ Features

- Satisfactory forward current transfer ratio h_{FE} collector current I_C characteristics.
- High collector-emitter voltage (Base open) V_{CEO}
- Small collector output capacitance (Common base, input open circuited) C_{ob}
- Makes up a complementary pair with 2SC2631, which is optimum for the pre-driver stage of a 20 W to 40 W output amplifier.

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	-150	V
Collector-emitter voltage (Base open)	V_{CEO}	-150	V
Emitter-base voltage (Collector open)	V_{EBO}	-5	V
Collector current	I_C	-50	mA
Peak collector current	I_{CP}	-100	mA
Collector power dissipation	P_C	750	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

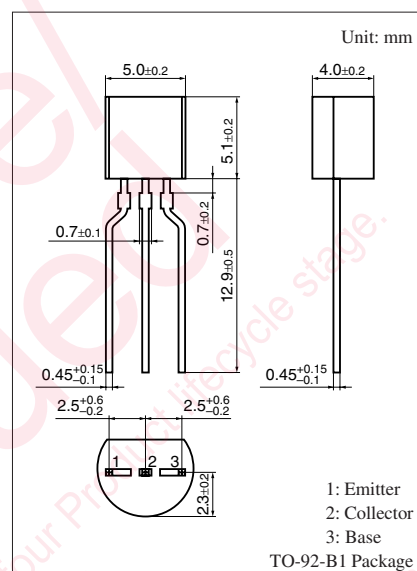
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

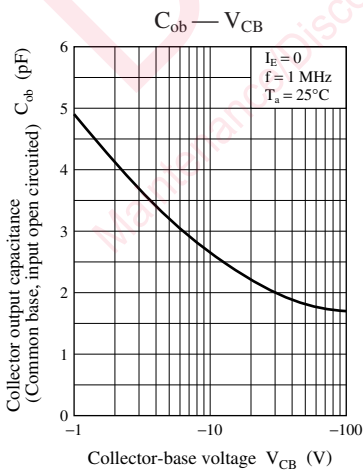
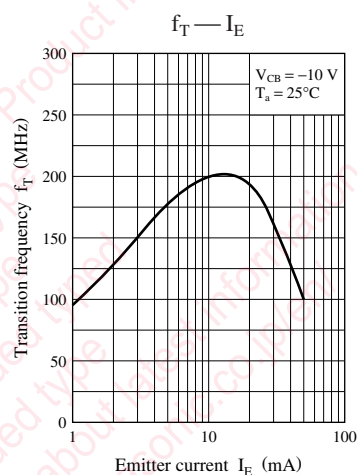
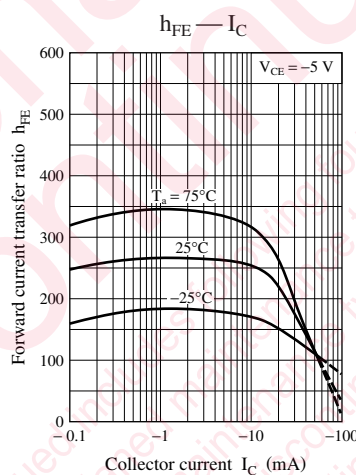
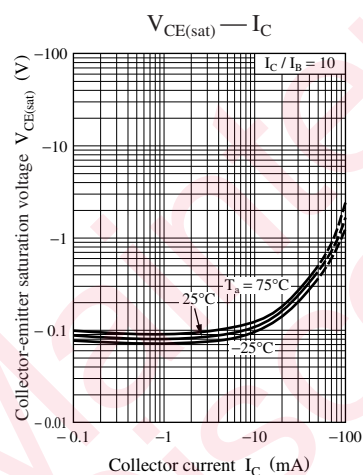
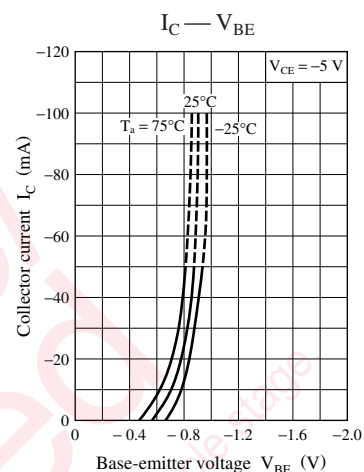
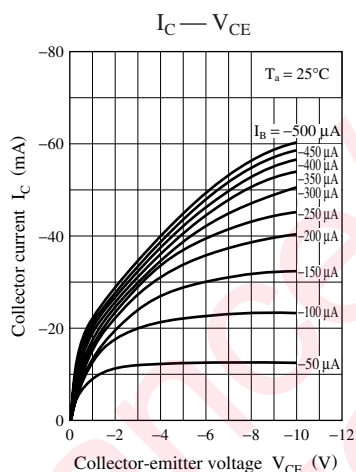
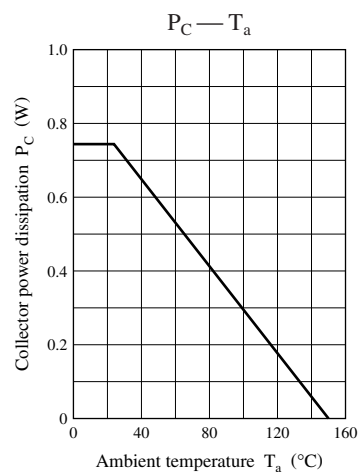
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -100\ \mu\text{A}$, $I_B = 0$	-150			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10\ \mu\text{A}$, $I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -100\ \text{V}$, $I_E = 0$			-1	μA
Forward current transfer ratio *	h_{FE}	$V_{CE} = -5\ \text{V}$, $I_C = -10\ \text{mA}$	130		450	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -30\ \text{mA}$, $I_B = -3\ \text{mA}$			-1	V
Transition frequency	f_T	$V_{CB} = -10\ \text{V}$, $I_E = 10\ \text{mA}$, $f = 200\ \text{MHz}$		200		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10\ \text{V}$, $I_E = 0$, $f = 1\ \text{MHz}$			5	pF
Noise voltage	NV	$V_{CE} = -40\ \text{V}$, $I_C = -1\ \text{mA}$, $G_V = 80\ \text{dB}$ $R_g = 100\ \text{k}\Omega$, Function = FLAT		150	300	mV

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	R	S	T
h_{FE}	130 to 220	185 to 330	260 to 450





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